

MOUNTING METHOD OF VIDEO SENSOR AND ADHESIVE TAPE USED THEREFOR

Publication number: JP2005341521 (A)

Publication date: 2005-12-08

Inventor(s): TAKANO HITOSHI; KONDO HIROYUKI; TERAJIMA TADASHI

Applicant(s): NITTO DENKO CORP

Classification:

- International: **H04N5/225; H04N5/225;** (IPC1-7): H04N5/225

- European:

Application number: JP20040223915 20040730

Priority number(s): JP20040133868 20040428; JP20040223915 20040730

Abstract of JP 2005341521 (A)

PROBLEM TO BE SOLVED: To provide a mounting method of a video sensor capable of attaining solder reflow in a state that an adhesive tape is adhered to a light receiving side of the video sensor and protecting the light receiving side of the video sensor even during the solder reflow in a mounting step of the video sensor employing a solid-state imaging device and to provide the protective adhesive tape used for the method. ; **SOLUTION:** The mounting method is characterized in that solder connection reflow is applied to terminals of the video sensor with a board side by heating the terminals at a temperature of 170 [deg.]C or over while the adhesive tape employing a polyimide film for a configuration material of the its material is adhered to the light receiving side of the video sensor. Further, at least a silicone group material is characterized in to be used for the adhesive configuration material of the adhesive tape. ; **COPYRIGHT:** (C)2006,JPO&NCIPI

Data supplied from the **esp@cenet** database — Worldwide